

**Amendment to the Specification:**

Page 12 – please replace the first complete paragraph with the following *new* paragraph:

In the embodiment of FIG. 2, it was also possible to plate the blind "vias" 15 simultaneous with plating of the PTHs. Of course, the internal "vias" 13 require plating prior to subsequent board lamination. Significantly, the teachings of this invention are applicable to such previous plating of thinner substrates for such eventual incorporation within a larger, multi-layered structure. As clearly seen in FIG. 2, the plating on the PTH (plated-through-hole) 11, defined earlier as of a possible thickness of about 0.5 mils to about 2.0 mils for holes having a diameter of about 8 mils to about 26 mils, does not entirely fill the hole but leaves it with a center opening which also extends entirely through the board thickness.